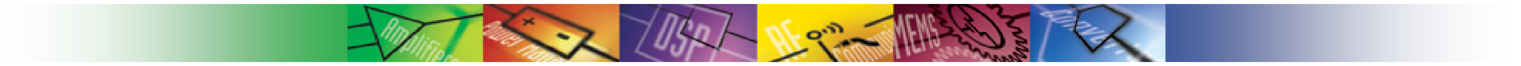

Product / Package Information	
Package	PDIP
Body Size	600 mils
Lead Count	28
Terminal Finish	100Sn

Environmental Compliance Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.22 E+00	87.7	877000	69.46	694576
Thermosets	Epoxy Resin	Proprietary	1.84 E-01	5.0	50000	3.96	39600
Thermosets	Phenol Resin	Proprietary	1.84 E-01	5.0	50000	3.96	39600
Thermosets	Epoxy Cresol Novolac	29690-82-2	7.34 E-02	2.0	20000	1.58	15840
Other inorganic materials	Carbon Black	1333-86-3	1.10 E-02	0.3	3000	0.24	2376
Subtotal			3.67 E+00	100	1000000	79.20	791991

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	8.76 E-01	97.50	975000	18.90	188973
Copper & its alloys	Iron	7439-89-6	2.11 E-02	2.35	23500	0.46	4555
Copper & its alloys	Zinc	7440-66-6	1.08 E-03	0.12	1200	0.02	233
Copper & its alloys	Phosphorus	7723-14-0	2.69 E-04	0.03	300	0.01	58
Subtotal			8.98 E-01	100.00	1000000	19.38	193818

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.31 E-03	100.0	1000000	0.05	498

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.21 E-02	100.0	1000000	0.69	6920

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.38 E-03	99.99	1000000	0.03	298

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.53 E-02	100.0	1000000	0.55	5457

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.78 E-03	80	800000	0.08	815
Thermosets	Epoxy Resin	Proprietary	7.08 E-04	15	150000	0.02	153
Others	Curing agent & hardener	Proprietary	2.36 E-04	5	50000	0.01	51
Subtotal			4.72 E-03	100	1000000	0.10	1018

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.63 E+00**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	PDIP
Body Size	600 mils
Lead Count	28
Terminal Finish	85Sn15Pb

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.22 E+00	87.7	877000	69.45	694532
Thermosets	Epoxy Resin	Proprietary	1.84 E-01	5.0	50000	3.96	39597
Thermosets	Phenol Resin	Proprietary	1.84 E-01	5.0	50000	3.96	39597
Thermosets	Epoxy Cresol Novolac	29690-82-2	7.34 E-02	2.0	20000	1.58	15839
Other inorganic materials	Carbon Black	1333-86-3	1.10 E-02	0.3	3000	0.24	2376
Subtotal			3.67 E+00	100	1000000	79.19	791941

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	8.76 E-01	97.57	975706	18.91	189098
Copper & its alloys	Iron	7439-89-6	2.05 E-02	2.28	22789	0.44	4417
Copper & its alloys	Zinc	7440-66-6	1.13 E-03	0.13	1263	0.02	245
Copper & its alloys	Phosphorus	7723-14-0	2.18 E-04	0.02	242	0.00	47
Subtotal			8.98 E-01	100.00	1000000	19.38	193806

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.31 E-03	100.0	1000000	0.05	498

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.73 E-02	85.0	850000	0.59	5881
Tin & its alloys	Lead	7439-92-1	4.81 E-03	15.0	150000	0.10	1038
Subtotal			3.21 E-02	100.0	1000000	0.69	6919

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.38 E-03	99.99	1000000	0.03	298

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.53 E-02	100.0	1000000	0.55	5456

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.78 E-03	80	800000	0.08	815
Thermosets	Epoxy Resin	Proprietary	7.08 E-04	15	150000	0.02	153
Others	Curing agent & hardener	Proprietary	2.36 E-04	5	50000	0.01	51
Subtotal			4.72 E-03	100	1000000	0.10	1018

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Dimethylsiloxane	68083-19-2	1.75 E-04	60.4	604000	0.004	38
Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	8.12 E-05	28.0	280000	0.002	18
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	2.90 E-05	10.0	100000	0.001	6
Other organic materials	Ethylbenzene	100-41-4	2.90 E-06	1.0	10000	0.00006	1
Other organic materials	Xylene	1330-20-7	1.74 E-06	0.6	6000	0.00004	0.4
Subtotal			2.90 E-04	100.0	1000000	0.01	63

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.63 E+00**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary